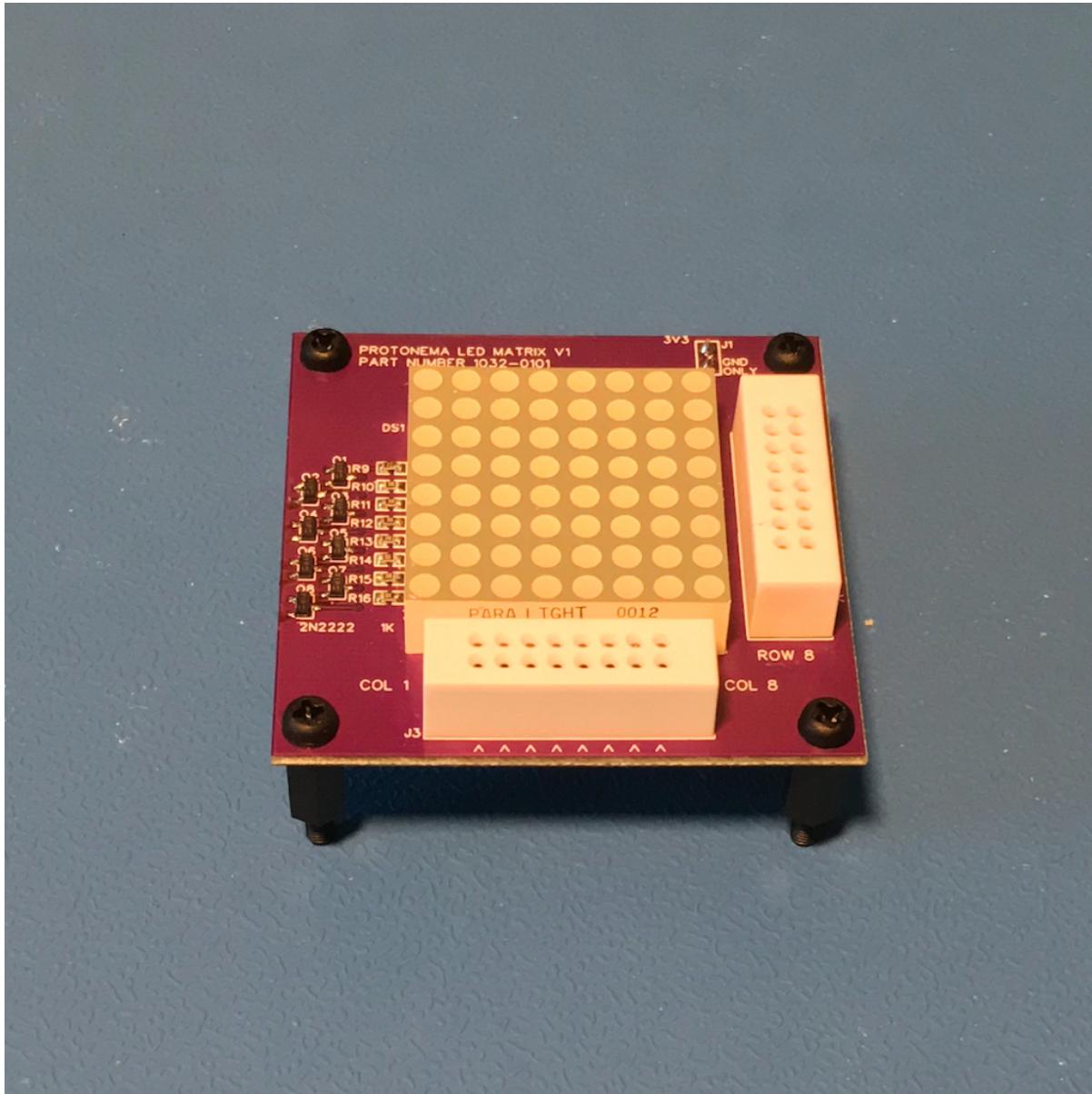


1

ASSEMBLY INSTRUCTIONS

2

3 1032A LED Matrix Stamp



6 Document control number: 1032-8010

7 Document date: 2022-12-10

8 Document revision: 1.0.0-draft.3

9 ABSTRACT: This document provides instructions on how to assemble and test a 1032A LED matrix stamp. A
complete bill of materials is included as an annex.

10 Suggestions and corrections should be directed to <http://www.github.com/dslik/protonema/issues>

11 Serial number: Assembly date: Assembled by:

12 USAGE

13 Copyright © 2022 David Slik (VE7FIM). All other trademarks or registered trademarks are the property of their
14 respective owners.

15 This source describes Open Hardware and is licensed under the CERN-OHL-S v2.

16 You may redistribute and modify this source and make products using it under the terms of the CERN-OHL-S v2
17 (https://ohwr.org/cern_ohl_s_v2.txt).

18 This source is distributed WITHOUT ANY EXPRESS OR IMPLIED WARRANTY, INCLUDING OF MER-
19 CHANTABILITY, SATISFACTORY QUALITY AND FITNESS FOR A PARTICULAR PURPOSE. Please see the
20 CERN-OHL-S v2 for applicable conditions.

21 Source location: <https://github.com/dslik/protonema/tree/main/stamps/1032A>

22 As per CERN-OHL-S v2 section 4, the following notice shall be displayed on product packaging and in the product
23 documentation:

24 "Based on the Protonema Electronics Prototyping and Learning System by David Slik -
25 <https://www.github.com/dslik/protonema/>"

26 All code fragments, scripts, and sample code in this document are made available under the following license:

27 BSD 3-Clause Software License

28 Copyright (c) 2022, David Slik (VE7FIM).

29 Redistribution and use in source and binary forms, with or without modification, are permitted provided that the
30 following conditions are met:

31 * Redistributions of source code must retain the above copyright notice, this list of conditions and the following
32 disclaimer.

33 * Redistributions in binary form must reproduce the above copyright notice, this list of conditions and the following
34 disclaimer in the documentation and/or other materials provided with the distribution.

35 * Neither the name of David Slik (VE7FIM) nor the names of its contributors may be used to endorse or promote
36 products derived from this software without specific prior written permission.

37 THIS SOFTWARE IS PROVIDED BY THE COPYRIGHT HOLDERS AND CONTRIBUTORS "AS IS" AND ANY
38 EXPRESS OR IMPLIED WARRANTIES, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF
39 MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE ARE DISCLAIMED. IN NO EVENT SHALL
40 THE COPYRIGHT OWNER OR CONTRIBUTORS BE LIABLE FOR ANY DIRECT, INDIRECT, INCIDENTAL, SPE-
41 CIAL, EXEMPLARY, OR CONSEQUENTIAL DAMAGES (INCLUDING, BUT NOT LIMITED TO, PROCUREMENT
42 OF SUBSTITUTE GOODS OR SERVICES; LOSS OF USE, DATA, OR PROFITS; OR BUSINESS INTERRUPTION)
43 HOWEVER CAUSED AND ON ANY THEORY OF LIABILITY, WHETHER IN CONTRACT, STRICT LIABILITY, OR
44 TORT (INCLUDING NEGLIGENCE OR OTHERWISE) ARISING IN ANY WAY OUT OF THE USE OF THIS SOFT-
45 WARE, EVEN IF ADVISED OF THE POSSIBILITY OF SUCH DAMAGE.

46 DISCLAIMER

47 The information contained in this publication is subject to change without notice. The author makes no warranty
48 of any kind with regard to this document, including, but not limited to, the implied warranties of merchantability
49 and fitness for a particular purpose. The author shall not be liable for errors contained herein or for incidental or
50 consequential damages in connection with the furnishing, performance, or use of this document.

51 Revision history

Table 1: Document Revisions

Version	Date	Change	Approver
1.0.0-draft.1	2022-12-04	Initial draft	D. Slik
1.0.0-draft.2	2022-12-08	Added missing RoHS certificate	D. Slik
1.0.0-draft.3	2022-12-10	Added missing photos (2.4.2, 8.1.1), added missing numbering	D. Slik

Table of contents

I 1032A assembly instructions	1
Section 1: Overview	2
Section 2: Prerequisites	3
2.1 Required safety training	3
2.2 Required skills training	4
Section 3: Preparation	5
3.1 Workspace	5
3.2 Project consumables	6
3.3 Project tools	7
3.4 Parts preparation	10
3.4.1 PCBs and PCBA	10
3.4.2 Reel cuttings	11
3.4.3 Loose components	13
3.4.4 Packaging materials	15
Section 4: Assembly	17
4.1 1032A assembly	17
Section 5: Test	20
5.1 Visual inspection	20
5.2 QC final check	21
5.3 QC PASS	22
5.4 QC FAIL	23
Section 6: Packaging	24
6.1 1032A packing	24
Section 7: Clean-up	27
7.1 Consumables	27
7.2 Tools	27
7.3 Workspace	28
Section 8: Record keeping	29
8.1 1032A record keeping	29
Section 9: Process improvement	31
9.1 Feedback	31
II 1032A Annexes	32
Section 10: Printed Circuit Boards	33
10.1 1032-0101 PCB	33
Section 11: Bill of materials	35
11.1 1032A LED Matrix Stamp	35
11.2 1032A Packaging	36
Section 12: Reduction of Hazardous Materials	37
12.1 MG Chemicals 4900	38
12.2 JLC lead-free PCB	39
12.3 PARALIGHT A3880E	40
12.4 Molex 0022284020	41
12.5 Cixi ZY28	42
12.6 Stackpole RMCF0603FT10K0	43
12.7 Stackpole RMCF0603FT649R	44

98	12.8 Nexperia MMBT2222A	45
99	12.9 M3 8mm Nylon Screw	46
100	12.10 M3 11mm Nylon Standoff	47
101	12.11 M3 Nylon Bolt	48

List of Figures

103	Fig. 1:	Assembly Desk	5
104	Fig. 2:	1 pair ESD gloves	6
105	Fig. 3:	1 spool MG Chemicals 4900 Lead Free No-Clean Wire Solder Sn96.2Ag2.8Cu0.4 (96.2/2.8/0.4) 20 AWG	6
106	Fig. 4:	Tools Container	7
107	Fig. 5:	Hozan F-23 components tray	7
108	Fig. 6:	ESD tweezers	8
109	Fig. 7:	3mm Phillips adjustable torque screwdriver	8
110	Fig. 8:	Fine-tipped Sharpie marker	8
111	Fig. 9:	Sissors	9
112	Fig. 10:	1x 1032-0101 v1.0 - LED Matrix Stamp PCB	10
113	Fig. 11:	Reels Container	11
114	Fig. 12:	8x 649 Ohm 0603 resistors	11
115	Fig. 13:	4x 10K Ohm 0603 resistors	12
116	Fig. 14:	4x MMBT2222A transistors	12
117	Fig. 15:	1x ZY28 - 16 Point solderless breadboard	13
118	Fig. 16:	1x A3880E - LED matrix display	13
119	Fig. 17:	1x 0022284020 - 1x2 2.54mm Male Header	13
120	Fig. 18:	4x 5mm M3 Nylon Screws	14
121	Fig. 19:	4x M3 11mm+6 Black Nylon Standoffs	14
122	Fig. 20:	4x M3 Black Nylon Nuts	14
123	Fig. 21:	1x QC Sticker	15
124	Fig. 22:	1x Long size anti-static bag	15
125	Fig. 23:	1x Small size anti-static bag	15
126	Fig. 24:	1x Packing box with foam inserts	16
127	Fig. 25:	2x 1032A Stickers	16
128	Fig. 26:	Roll of packing tape	16
129	Fig. 27:	1032-0101 PCB with Q1-Q8 soldered on.	17
130	Fig. 28:	1032-0101 PCB with R1-R8 soldered on.	17
131	Fig. 29:	1032-0101 PCB with R9-R16 soldered on.	18
132	Fig. 30:	1032-0101 PCB with J1 soldered on.	18
133	Fig. 31:	1032-0101 PCB with the display module soldered on.	18
134	Fig. 32:	1032-0101 PCB with the two breadboard modules soldered on.	19
135	Fig. 33:	1032-0101 PCB with four nylon posts attached.	19
136	Fig. 34:	Powered 1032-0101 PCB driven by a 1031A.	21
137	Fig. 35:	1032A with QC Passed sticker	22
138	Fig. 36:	1032A in anti-static bag.	23
139	Fig. 37:	1032A in QC Fail bin.	23
140	Fig. 38:	1032A in anti-static bag.	24
141	Fig. 39:	Anti-static bag with nylon nuts in the small anti-static bag.	24
142	Fig. 40:	1028A in anti-static bag with sticker.	25
143	Fig. 41:	Example photographs of the sealed bag with the serial number written on the sticker	25
144	Fig. 42:	1032A in box.	25
145	Fig. 43:	1032A in box, sealed with ESD tape.	26
146	Fig. 44:	1032A in box with sticker.	26
147	Fig. 45:	1032A in box with sticker with serial number.	26
148	Fig. 46:	Clean assembly workstation	28
149	Fig. 47:	Example of serial number on document cover	29
150	Fig. 48:	1032-0101 PCB Front	33
151	Fig. 49:	1032-0101 PCB Rear	34

List of Tables

154	Table 1: Document Revisions	ii
155	Table 2: Safety training	3
156	Table 3: Skills training	4
157	Table 4: Prepare workspace	5
158	Table 5: Assembly consumables	6
159	Table 6: Assembly tools	7
160	Table 7: PCBs and PCBA	10
161	Table 8: Assembly reels	11
162	Table 9: Loose components	13
163	Table 10: Packaging materials	15
164	Table 11: 1032A assembly steps	17
165	Table 12: 1032A visual inspection	20
166	Table 13: 1032A QC final check	21
167	Table 14: 1032A QC approval	22
168	Table 15: 1032A QC fail	23
169	Table 16: 1032A packaging	24
170	Table 17: Consumables cleanup	27
171	Table 18: Tools cleanup	27
172	Table 19: Workspace cleanup	28
173	Table 20: 1032A record keeping	29
174	Table 21: 1032-0101 PCB	33
175	Table 22: 1032A parts	35
176	Table 23: 1032A packing parts	36
177	Table 24: MG Chemicals 4900 RoHS Compliance	38
178	Table 25: JLC PCB RoHS Compliance	39
179	Table 26: PARALIGHT A3880E RoHS Compliance	40
180	Table 27: Molex 0022284020 RoHS Compliance	41
181	Table 28: Cixi ZY28 Compliance	42
182	Table 29: Stackpole RMCF0603FT10K0 RoHS Compliance	43
183	Table 30: Stackpole RMCF0603FT649R RoHS Compliance	44
184	Table 31: Nexperia MMBT2222A RoHS Compliance	45
185	Table 32: M3 8mm Nylon Screw RoHS Compliance	46
186	Table 33: M3 11mm Nylon Standoff RoHS Compliance	47
187	Table 34: M3 Nylon Bolt RoHS Compliance	48

188

Part I

189

1032A assembly instructions

190 Section 1

191 Overview

192 This document describes the materials, processes, outcomes and verifications required to successfully assemble
193 and test a 1032A LED matrix stamp, a sub-component of the Protonema electronics prototyping and learning
194 system.

195 A first-time reader should carefully review section 2 - prerequisites, and section 3 - preparation before beginning
196 the assembly process.

197 This document serves both as instructions and as a record of the assembly of the product. When you finish each
198 step in this document, sign your name (or apply your stamp) in the "Signature/Stamp" box on the right to provide a
199 record of completion.

200 When things go wrong, this document provides guidance for common issues that have been encountered in the
201 past. When this document does not provide guidance, please contact your quality management representative,
202 who will help you fill out an exception report. These reports help improve process quality and product quality, and
203 these reports are incorporated into future revisions of this document.

204 Always remember: If you are unable to successfully complete these instructions, that means the processes supporting
205 you (including this document) have failed you. Our processes are built for your success, and by improving our processes, we help everyone succeed.

207 Section 2

208 Prerequisites

209 2.1 Required safety training

- 210** The following safety training units must be completed before assembling this product.
211 By signing (or applying your stamp) on the right, you indicate that you have completed the following training:

Table 2: Safety training

Item #	Description	Signature/Stamp
2.1.1	0102-0100 - Safety reporting policies and procedures training Key topics: Understanding policies and procedures around how to identify, contain and report a safety-related issue in the workplace, including damaged or malfunctioning equipment, leaks, spills, and other occupational hazards.	Stamp or sign here
2.1.2	0102-0101 - Material safety data sheets training Key topics: Understanding how to read material safety data sheets (MSDS) for materials you will be handling during product assembly, how they can affect your health and the health of the environment, how to safely handle and dispose of them, and what to do if there is a spill or accidental exposure.	Stamp or sign here
2.1.3	0102-0102 - Solder handling and disposal policies and procedures training Key topics: Understanding policies and procedures related to handling solder and solder paste, stencil cleaning, and solder disposal.	Stamp or sign here
2.1.4	0102-0105 - Electro-static discharge controls policies and procedures training Key topics: Understanding policies and procedures related to protecting equipment and components from electro-static discharge, including clothing, protective equipment, material handling and labelling.	Stamp or sign here

2.2 Required skills training

- ²¹² The following skills training units must be completed before assembling this product.
²¹⁴ By signing (or applying your stamp) on the right, you indicate that you have completed the following training:

Table 3: Skills training

Item #	Description	Signature/Stamp
2.2.1	0103-0202 - ANSI/ESD S20.20 Electro-static discharge controls Key topics: Understanding of ESD safety, the ESD control program, equipment and personnel grounding, EPAs, packaging and marking.	Stamp or sign here
2.2.2	0103-0203 - General components handling Key topics: Understanding of safe component handling, including reeled components, components in JEDEC trays, and loose components. Includes avoiding contamination, moisture control, and component inventory management.	Stamp or sign here
2.2.3	0103-0414 - 5040-XTS reflow station Key topics: Safe and effective use of the 5040-XTS reflow station, including use of the pre-heater, the hot air system, and the soldering iron. Covers inspection and verification, cleaning, preferred settings and best practice techniques.	Stamp or sign here
2.2.4	0103-0301 - IPC-A-610G - Acceptability of electronic assemblies Key topics: Covers visual acceptability requirements for electronic assemblies, including handling considerations, hardware installation, component placement, soldering, terminal connections, wiring, marking and cleanliness.	Stamp or sign here
2.2.5	0103-0302 - IPC-J-STD-001F - Soldered electrical connections Key topics: Covers soldering materials, general soldering and assembly requirements, wire and terminal connections, through-hole mounting, surface mounting of components, cleaning process requirements, PCB requirements, coatings and product assurance.	Stamp or sign here

215 Section 3

216 Preparation

217 3.1 Workspace

- 218 Before starting assembly, check out an assembly desk for a minimum of one hour. Units are assembled in batches
 219 of four, with each batch taking 20 minutes.

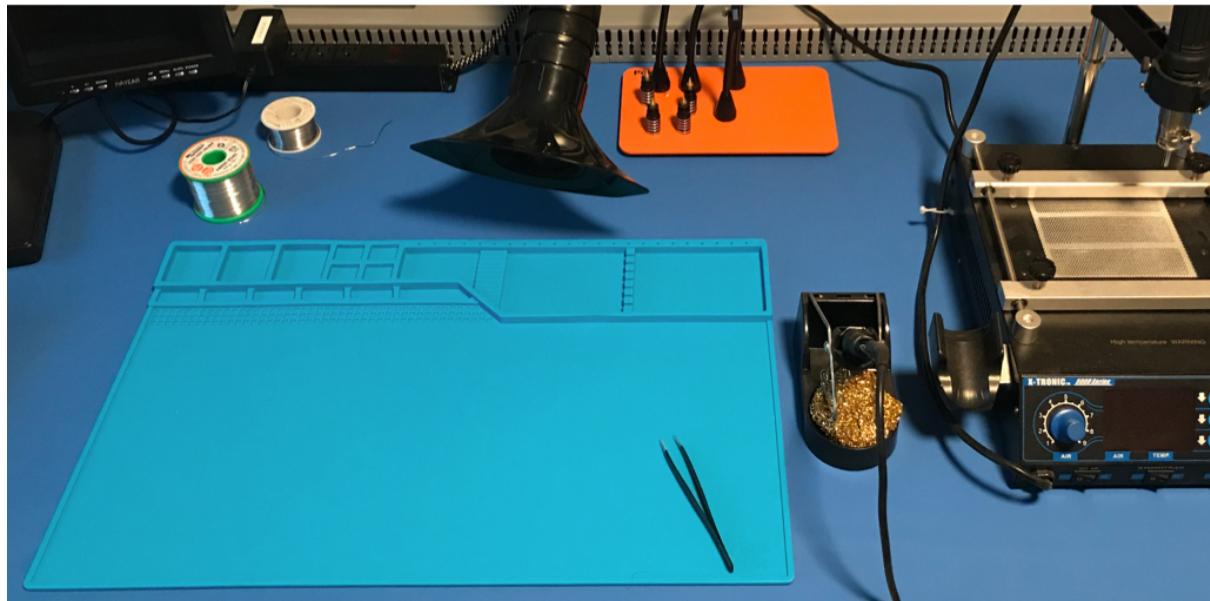


Fig. 1: Assembly Desk

Table 4: Prepare workspace

Step	Description	Signature/Stamp
3.1.1	Verify that the workspace has a clean assembly mat and anti-static mat, and that the cleaning record has been signed since last use.	Stamp or sign here
3.1.2	Verify that the HEPA fume extractor turns on, and you can feel air suction from the nozzle.	Stamp or sign here

continues on next page

Table 4 – continued from previous page

Step	Description	Signature/Stamp
3.1.3	Verify that the 5040-XTS rework station soldering iron tip is not worn down. If it is worn down, obtain a new 900M-T-I tip from the stores department.	Stamp or sign here
3.1.4	Verify that the heating surface of the MHP30 hot plate is clean.	Stamp or sign here

220 3.2 Project consumables

221 Obtain each of the below consumable items from the stores department:

Table 5: Assembly consumables

Item #	Description	Signature/Stamp
3.2.1	 <p>Fig. 2: 1 pair ESD gloves If you prefer to use your own pair of ESD gloves, make sure they are tested before use.</p>	Stamp or sign here
3.2.2	 <p>Fig. 3: 1 spool MG Chemicals 4900 Lead Free No-Clean Wire Solder Sn96.2Ag2.8Cu0.4 (96.2/2.8/0.4) 20 AWG</p>	Stamp or sign here

222 3.3 Project tools

- 223 Obtain a tools container labelled “1XXX Assembly Tools” from the 1XXX section of the stores supply shelf. At your assembly desk, use [Table 6](#) to verify that all the required tools are present.
- 224 If any required tools are missing, return all tools and the tools container to the stores department, and obtain another tools container.

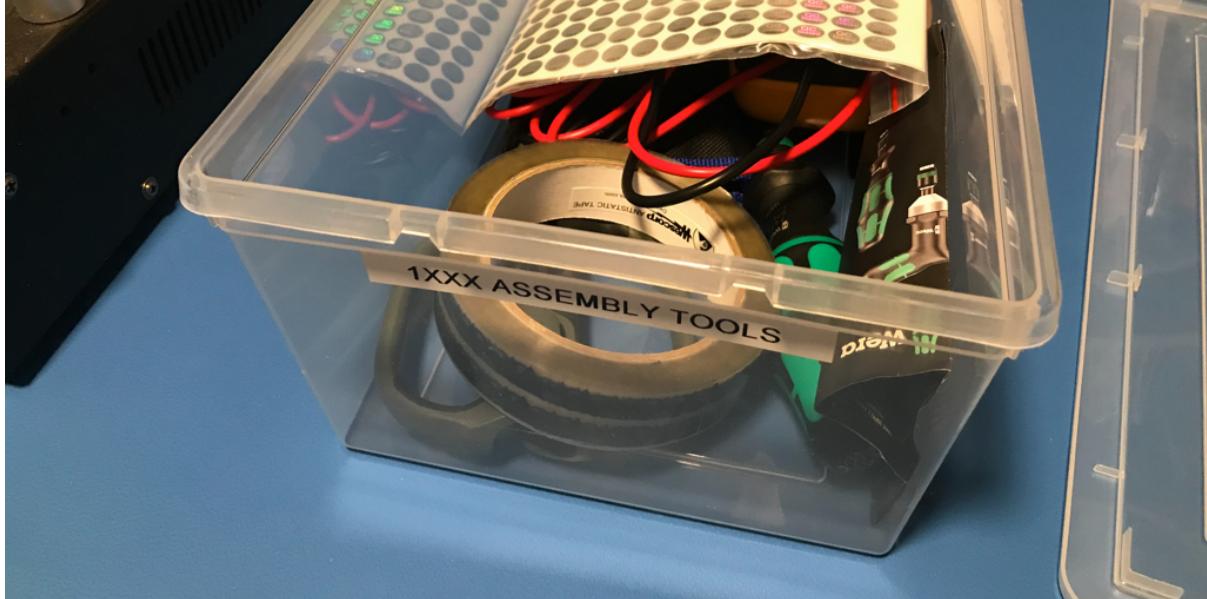


Fig. 4: Tools Container

- 227 Remove each of the following tools from the tools container, and place them on the anti-static mat of the assembly desk:
- 228

Table 6: Assembly tools

Item #	Description	Signature/Stamp
3.3.1		Stamp or sign here

Fig. 5: Hozan F-23 components tray

continues on next page

Table 6 – continued from previous page

Item #	Description	Signature/Stamp
3.3.2	 Fig. 6: ESD tweezers	 Stamp or sign here
3.3.3	 Fig. 7: 3mm Phillips adjustable torque screwdriver	 Stamp or sign here
3.3.4	 Fig. 8: Fine-tipped Sharpie marker	 Stamp or sign here

continues on next page

Table 6 – continued from previous page

Item #	Description	Signature/Stamp
3.3.5	 Fig. 9: Scissors	Stamp or sign here

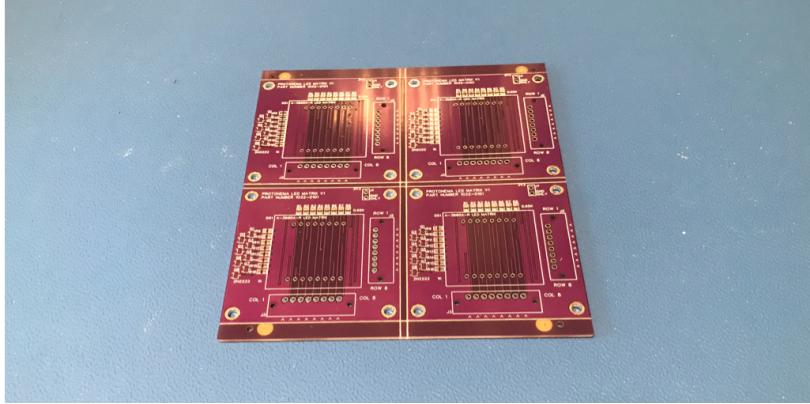
229 **3.4 Parts preparation**

230 **3.4.1 PCBs and PCBAs**

231 NOTICE: All PCBs and PCBAs must be handled with gloves to prevent marking with skin oils.

232 NOTICE: PCBs are removed from manufacturer packaging only when needed.

Table 7: PCBs and PCBAs

Item #	Description	Signature/Stamp
3.4.1.1	No marking required  Fig. 10: 1x 1032-0101 v1.0 - LED Matrix Stamp PCB	Stamp or sign here

233 3.4.2 Reel cuttings

- 234 All reels are stored in the bin labelled "1XXX Reels" on the shelf labelled "1XXX Components". As this is a manually
 235 assembled product (no automated pick-and-place), tape should be cut off as needed for the number of units being
 236 assembled, and placed in the assembly tray.

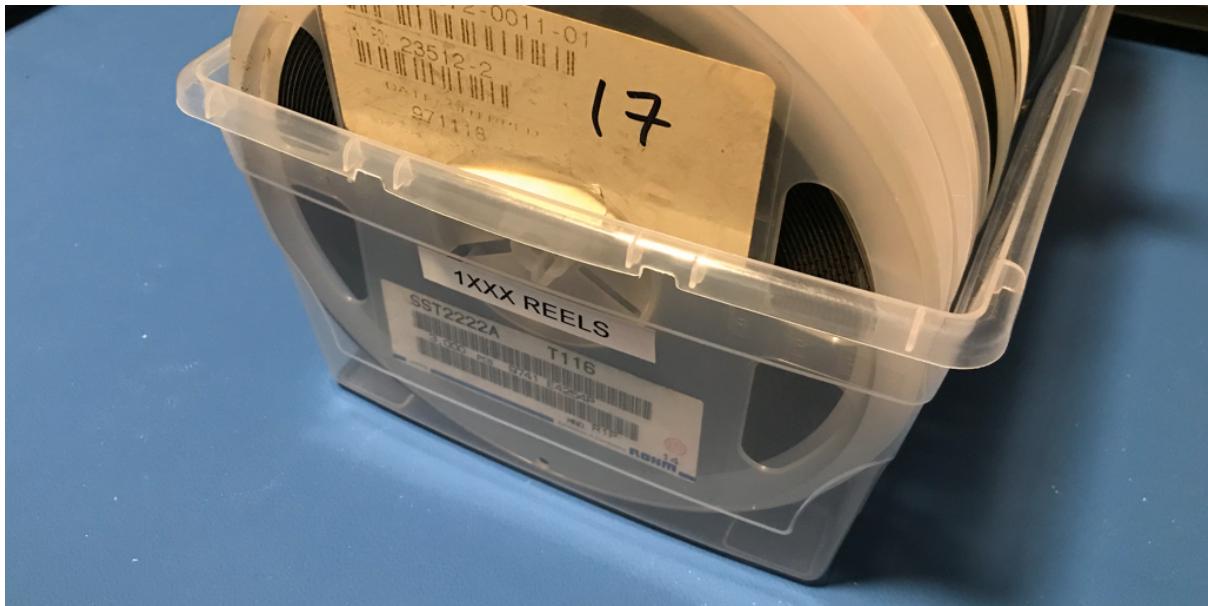


Fig. 11: Reels Container

- 237 Cut off the indicated number of parts (multiplied by the number of units to be assembled), and mark them with the
 238 value:

Table 8: Assembly reels

Reel #	Description	Signature/Stamp
1	<p>Mark with "649R"</p>	<p>Stamp or sign here</p>

Fig. 12: 8x 649 Ohm 0603 resistors

continues on next page

Table 8 – continued from previous page

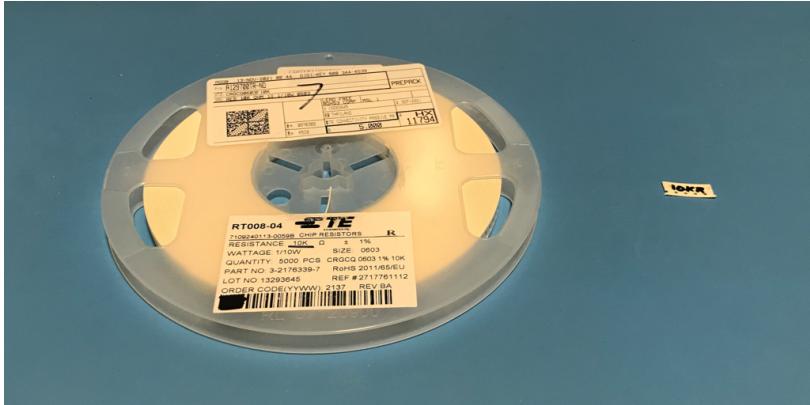
Reel #	Description	Signature/Stamp
7	Mark with "10KR" 	Stamp or sign here
17	No marking required 	Stamp or sign here

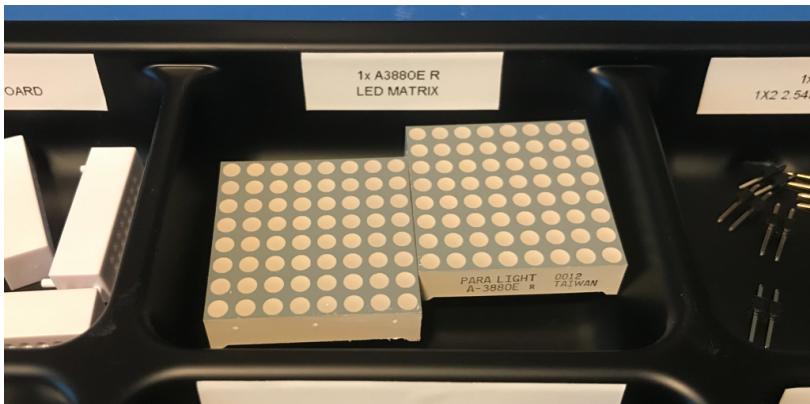
Fig. 14: 4x MMBT2222A transistors

²³⁹ Be sure to return the 1XXX Reels bin as soon as you have finished cutting off the required parts.

240 3.4.3 Loose components

241 All loose components are stored on the shelf labelled “1XXX Components”. Take the components tray and obtain the following quantities of the following parts:

Table 9: Loose components

Item #	Description	Signature/Stamp
3.4.3.1	No marking required  Fig. 15: 1x ZY28 - 16 Point solderless breadboard	Stamp or sign here
3.4.3.2	No marking required  Fig. 16: 1x A3880E - LED matrix display	Stamp or sign here
3.4.3.3	No marking required  Fig. 17: 1x 0022284020 - 1x2 2.54mm Male Header	Stamp or sign here

continues on next page

Table 9 – continued from previous page

Item #	Description	Signature/Stamp
3.4.3.4	No marking required 	Stamp or sign here
3.4.3.5	No marking required 	Stamp or sign here
3.4.3.6	No marking required 	Stamp or sign here

243 3.4.4 Packaging materials

- 244 All packaging materials are stored on the shelf labelled "1XXX Components". Take the packaging box and obtain
245 the following quantities of the following materials:

Table 10: Packaging materials

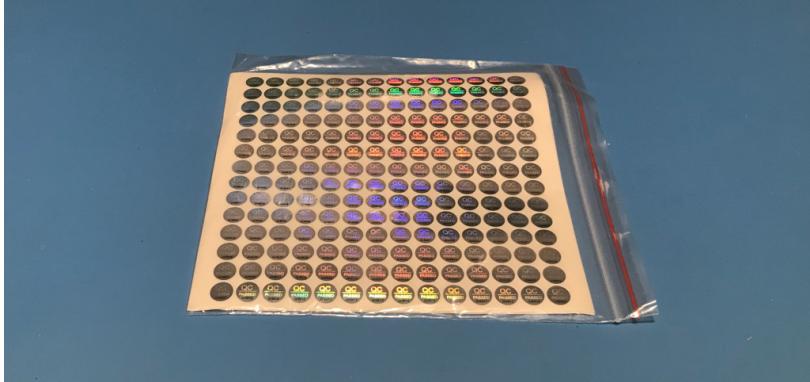
Item #	Description	Signature/Stamp
3.4.4.1	No marking required 	Stamp or sign here
3.4.4.2	No marking required 	Stamp or sign here
3.4.4.3	No marking required 	Stamp or sign here

Fig. 21: 1x QC Sticker

continues on next page

Table 10 – continued from previous page

Item #	Description	Signature/Stamp
3.4.4.4	No marking required 	Stamp or sign here
3.4.4.5	No marking required 	Stamp or sign here
3.4.4.6	No marking required 	Stamp or sign here

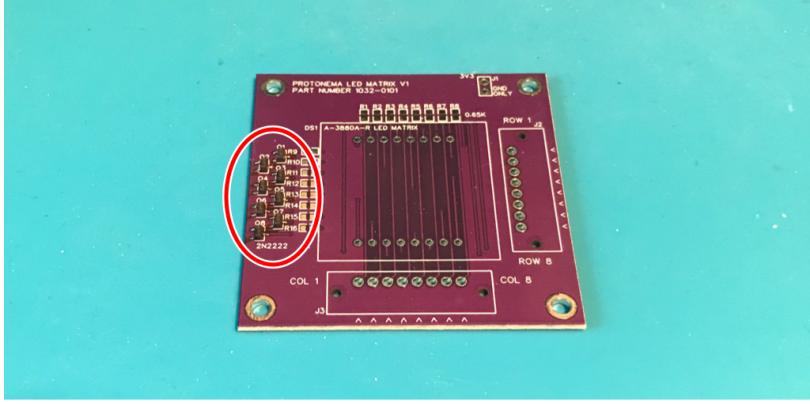
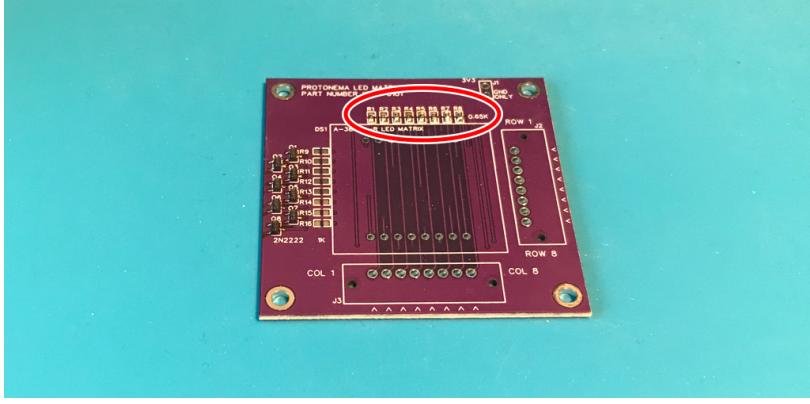
246 Section 4

247 Assembly

248 4.1 1032A assembly

249 This assembly step takes 5 minutes.

Table 11: 1032A assembly steps

Step #	Description	Signature/Stamp
4.1.1	Solder Q1 through Q8 onto the 1032-0101 PCB. 	Stamp or sign here
4.1.2	Solder R1 through R8 onto the 1032-0101 PCB. 	Stamp or sign here

continues on next page

Table 11 – continued from previous page

Step #	Description	Signature/Stamp
4.1.3	Solder R9 through R16 onto the 1032-0101 PCB.	Stamp or sign here
4.1.4	Insert the 2 pin header into J1 from the rear of the board, flip the board, and solder one pin of the header on, flip the board again and sure it is 90 degrees to the board, then solder the remaining pin.	Stamp or sign here
4.1.5	Insert the A3880E display module with the part number label facing down. Flip the board, and solder the display connectors, making sure that the display module pins are consistently at the top of the through holes.	Stamp or sign here

Fig. 29: 1032-0101 PCB with R9-R16 soldered on.

continues on next page

Table 11 – continued from previous page

Step #	Description	Signature/Stamp
4.1.6	Insert the two breadboard modules, then solder.	
4.1.7	For each of the four corner holes, attach a nylon screw to a nylon post through the hole.	

Fig. 32: 1032-0101 PCB with the two breadboard modules soldered on.

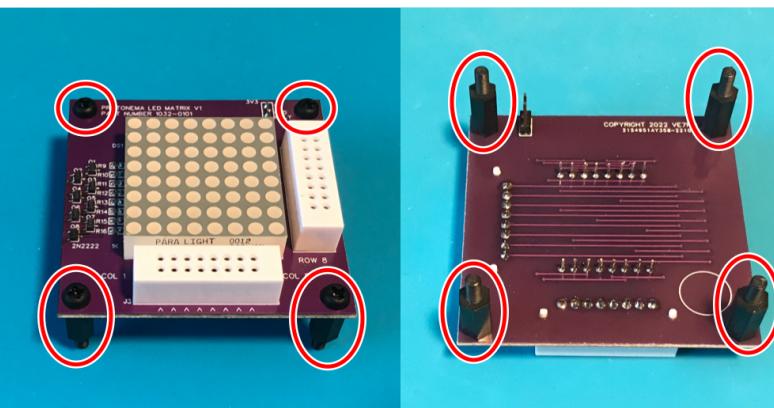


Fig. 33: 1032-0101 PCB with four nylon posts attached.

250 **Section 5**

251 **Test**

252 **5.1 Visual inspection**

253 This test process takes 2 minutes.

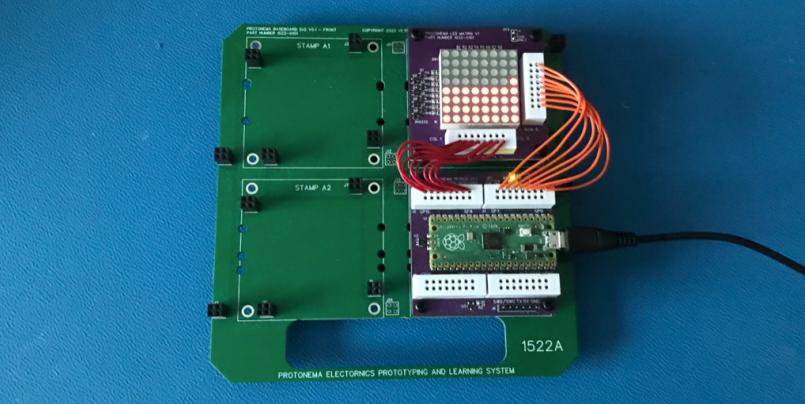
Table 12: 1032A visual inspection

Step #	Description	Signature/Stamp
5.1.1	Verify that there are no loose parts.	Stamp or sign here
5.1.2	Verify that there are no visible fingerprints.	Stamp or sign here

254 5.2 QC final check

255 This test process takes 2 minutes.

Table 13: 1032A QC final check

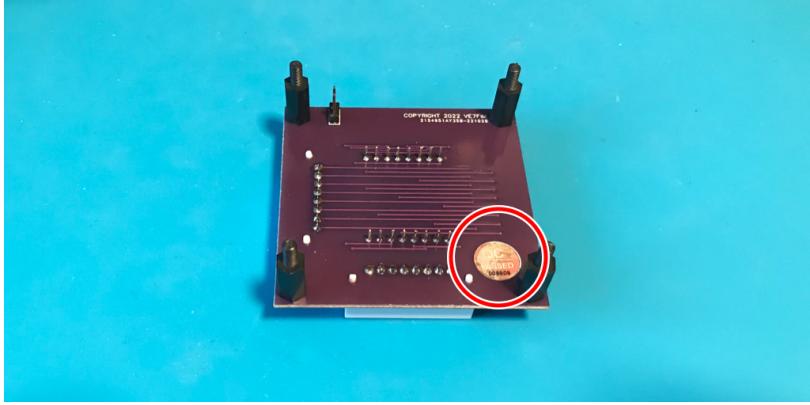
Step #	Description	Signature/Stamp
5.2.1	<p>Connect the 1032A to a baseboard and to a pre-programmed 1031A, as shown below. Connect power and verify that all of the LEDs light up in sequence.</p> <p>If test does not pass, write down the unexpected behaviour in the "Signature/Stamp" column on the right.</p>  <p>Fig. 34: Powered 1032-0101 PCB driven by a 1031A.</p>	Stamp or sign here

256 5.3 QC PASS

257 Only perform these steps if all QC checks have passed.

258 This test process takes 1 minutes.

Table 14: 1032A QC approval

Step #	Description	Signature/Stamp
5.3.1	Using the tweezers, affix QC Passed sticker in location shown below, then write down the serial number from the QC sticker below the "Signature/Stamp" in the column to the right. 	Stamp or sign here
5.3.2	Take two photographs, one of the front of the 1032A, and one of the back of the 1032A.	Stamp or sign here

259 5.4 QC FAIL

- 260 Only perform these steps if any QC check have failed.
 261 This test process takes 2 minutes.

Table 15: 1032A QC fail

Step #	Description	Signature/Stamp
5.4.1	Place the 1032A module in the anti-static bag. 	Stamp or sign here
5.4.2	Take an A4 plastic bag, and place the 1032A, along with this document, in the "QC Fail" bin 	Stamp or sign here

Fig. 36: 1032A in anti-static bag.

FPO

Fig. 37: 1032A in QC Fail bin.

262 Section 6

263 Packaging

264 6.1 1032A packing

265 This packaging process takes 3 minutes.

Table 16: 1032A packaging

Step #	Description	Signature/Stamp
6.1.1	Place the 1032A module in the anti-static bag. 	Stamp or sign here
6.1.2	Place four nylon nuts in a small anti-static bag, and add the bottom of the bag to the bag the 1032A module is in. 	Stamp or sign here

Fig. 38: 1032A in anti-static bag.

continues on next page

Table 16 – continued from previous page

Step #	Description	Signature/Stamp
6.1.3	Seal the anti-static bag with a 1032A sticker.	Stamp or sign here
		
	Fig. 40: 1028A in anti-static bag with sticker.	
6.1.4	Using the Sharpie pen, Write down the serial number of the 1032A on the sticker, at the end of the line listing the 1032A.	Stamp or sign here
		
	Fig. 41: Example photographs of the sealed bag with the serial number written on the sticker	
6.1.5	Place 1032A bag in the box on top of the bottom foam padding.	Stamp or sign here
		
	Fig. 42: 1032A in box.	
6.1.6	Take a photograph of the 1032A in the box.	Stamp or sign here

continues on next page

Table 16 – continued from previous page

Step #	Description	Signature/Stamp
6.1.7	Using the ESD tape, secure the lid of the box. 	Stamp or sign here
6.1.8	Affix a 1032A sticker to the lid of the box. 	Stamp or sign here
6.1.9	Using the Sharpie pen, Write down the serial number of the 1032A on the sticker, at the end of the line listing the 1032A. 	Stamp or sign here
6.1.10	Take a photograph of the sealed 1032A box.	Stamp or sign here

266 Section 7

267 Clean-up

268 7.1 Consumables

269 This packaging process takes 5 minutes.

Table 17: Consumables cleanup

Step #	Description	Signature/Stamp
7.1.1	If the ESD gloves have contacted solder paste, or are soiled, they shall be disposed of in the standard waste bin.	Stamp or sign here
7.1.2	If there is unused solder wire on the spool, it shall be returned to stores.	Stamp or sign here
7.1.3	Loose component packaging shall be disposed of in the standard waste bin.	Stamp or sign here

270 7.2 Tools

271 This cleanup process takes 5 minutes.

Table 18: Tools cleanup

Step #	Description	Signature/Stamp
7.2.1	All tools shall be returned to the assembly tools container, and returned to the stores supply shelf. If any tools are damaged or worn, return the container to stores, and let the manager know which tool is damaged or worn.	Stamp or sign here

continues on next page

Table 18 – continued from previous page

Step #	Description	Signature/Stamp
7.2.2	Remove this document from the springback binder.	Stamp or sign here
7.2.3	Print a new copy of this document, and insert it into the springback binder that this document was originally in.	Stamp or sign here
7.2.4	Return the springback binder with the newly printed document to the 1032A section of the store supply shelf.	Stamp or sign here

272 7.3 Workspace

273 This packaging process takes 5 minutes.

Table 19: Workspace cleanup

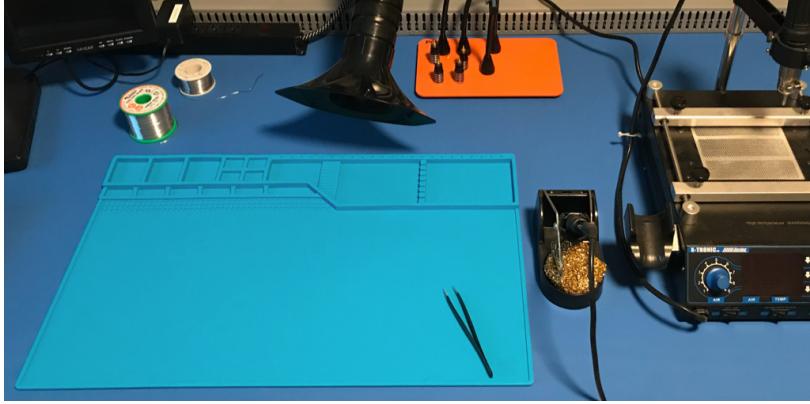
Step #	Description	Signature/Stamp
7.3.1	Make sure that the workspace is clean and as it was when you started the assembly. 	Stamp or sign here

Fig. 46: Clean assembly workstation

274 Section 8

275 Record keeping

276 8.1 1032A record keeping

277 This packaging process takes 5 minutes.

Table 20: 1032A record keeping

Step #	Description	Signature/Stamp
8.1.1	<p>Write the serial number, the date, and your first and last name in large print on the bottom of the front cover of this document.</p>	Stamp or sign here
8.1.2	Create a new folder under the 1032A folder, named with the serial number.	Stamp or sign here
8.1.3	Copy all photos taken during the assembly process into the newly created folder in step #2.	Stamp or sign here
8.1.4	Remove this document from the binding clamps, scan the document, and save the scanned PDF into the newly created folder in step #2, with the name "1032A-SNAAAAAA.pdf", where AAAAAA is replaced with the serial number.	Stamp or sign here

continues on next page

Table 20 – continued from previous page

Step #	Description	Signature/Stamp
8.1.5	Three-hole punch the document, then file it at the end of the current month's assembly records binder.	 Stamp or sign here
8.1.6	Add an entry to the assembly records binder, "<Date> - 1032A - SN# AAAAAAA - <Your Name>", where <Date> is replaced with today's date in ISO-8601 YYYY-MM-DD, where AAAAAAA is replaced with the serial number of the 1032A, and where <Your Name> is replaced with your first and last name.	 Stamp or sign here

278 **Section 9**

279 **Process improvement**

280 **9.1 Feedback**

281 Please submit an issue to the [Protonema Issue Repository](http://www.github.com/dslik/protonema/issues) (<http://www.github.com/dslik/protonema/issues>) if you
282 encounter any of the below situations:

- 283 • Error in this document
- 284 • Unclear directions
- 285 • Suggested process improvements
- 286 • Results of QC failure investigations
- 287 • Tool change suggestions

288 Qualtiy processes and documentation is a team effort. This document would not exist without the participation and
289 contributions of the entire assebly team.

290 Thank you for reading this assembly instructions document.

291 End of document.

292

Part II

293

1032A Annexes

294

Section 10

295

Printed Circuit Boards

296

10.1 1032-0101 PCB

Table 21: 1032-0101 PCB

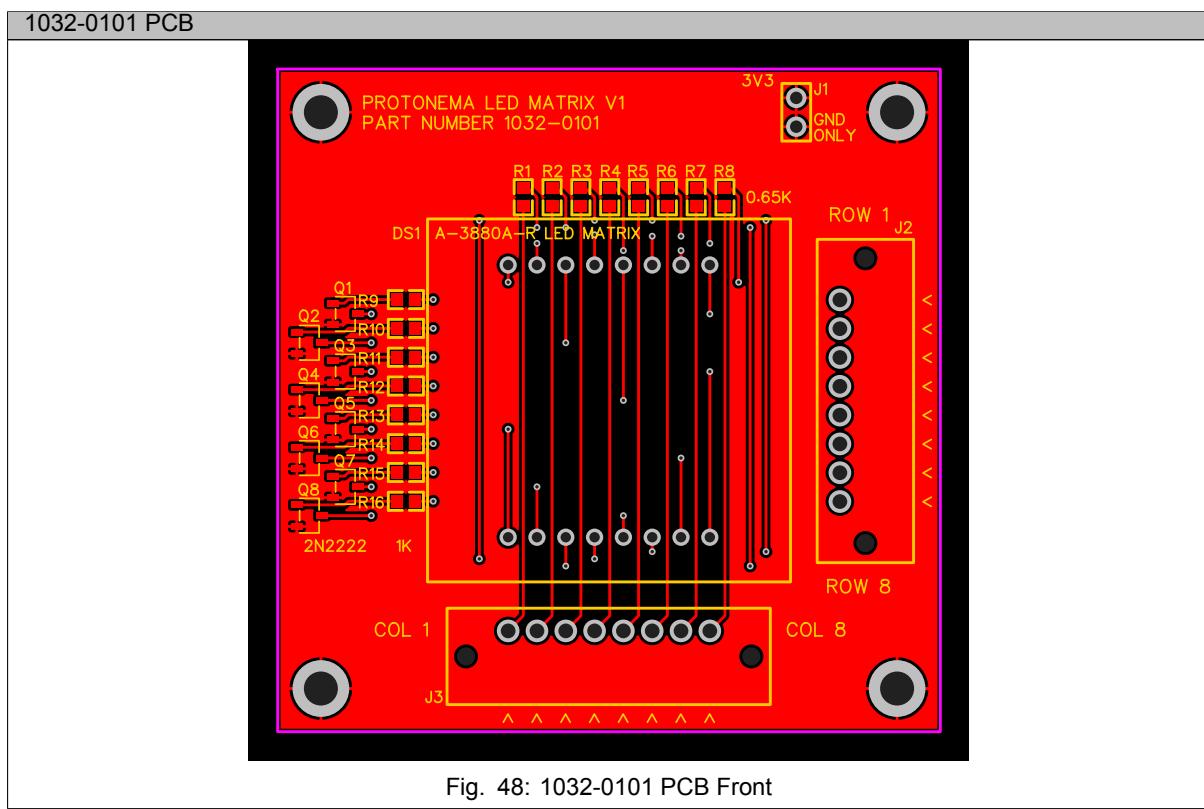
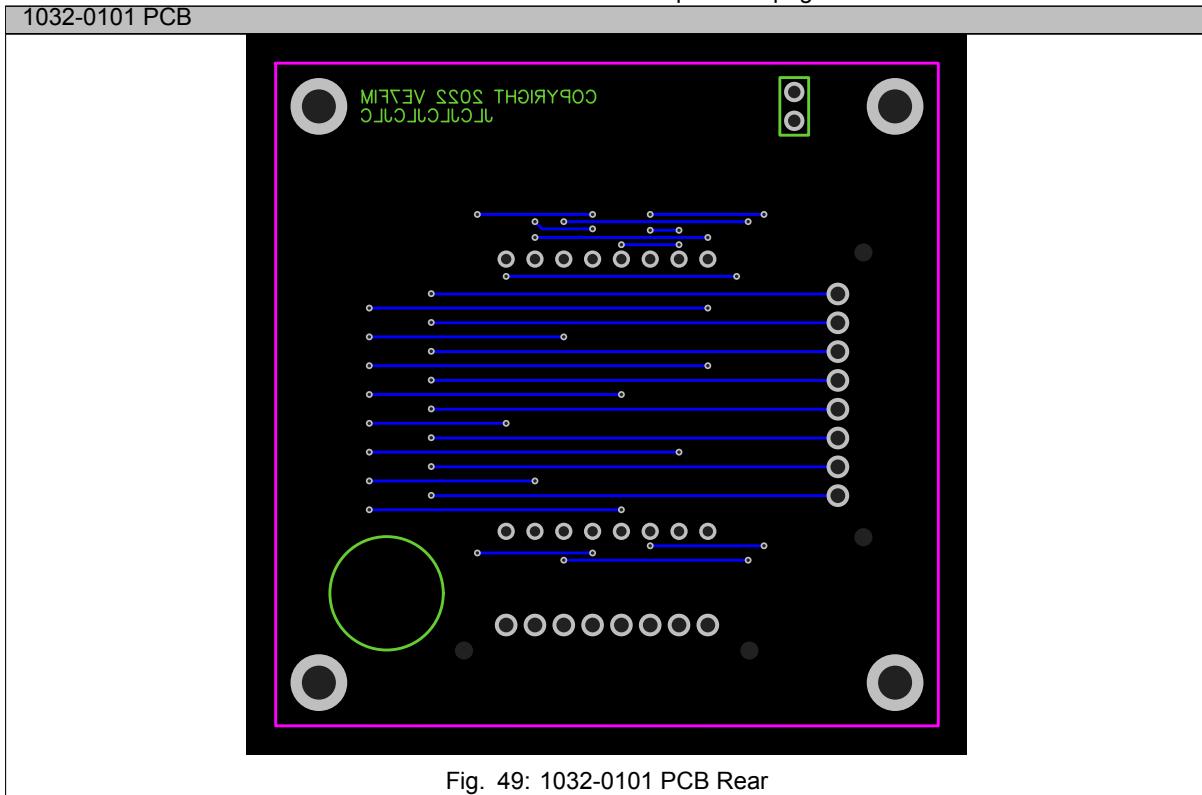


Fig. 48: 1032-0101 PCB Front

continues on next page

Table 21 – continued from previous page



297 Section 11

298 Bill of materials

299 11.1 1032A LED Matrix Stamp

300 The parts required to assemble a 1032A are listed in Table 22.

Table 22: 1032A parts

Reference Designation	Qty	Description	Manufacturer	Manufacturer Part Number	Supplier	Cost
1032-0101	1	Stamp PCB	JLCPCB	Y358-2154951A	JLCPCB	\$0.59 CAD
DS1	1	8x8 32mm LED Matrix Display	Paralight	A3880E	Tayda	\$1.82
J1	1	Connector Header Through Hole 2 position 0.100" (2.54mm)	Molex	0022284020	Digikey	\$0.17 CAD
J2, J3	2	16 Point solderless breadboard	Cixi Zhongyi Electronics Factory	ZY28	Zhongyi	\$2.54 CAD
R1 - R8	8	649 Ohms $\pm 1\%$ 0.1W, 1/10W Chip Resistor 0603 (1608 Metric)	Stackpole Electronics Inc	RMCF0603FT649R	Digikey	\$1.28 CAD
R9 - R16	8	10K Ohms $\pm 1\%$ 0.1W, 1/10W Chip Resistor 0603 (1608 Metric)	Stackpole Electronics Inc	RMCF0603FT10K0	Digikey	\$1.28 CAD
Q1 - Q8	8	Bipolar (BJT) Transistor NPN 40V 600mA SOT-23	Nexperia USA Inc.	MMBT2222A	Digikey	\$1.76 CAD
MP1 - MP4	4	Screw - M3 5mm Black Nylon Phillips Socket Button Head	Order By Description			\$0.25 CAD
MP5 - MP8	4	Standoff - M3 11mm+6 Black Nylon	Order By Description			\$0.30 CAD
MP9 - MP12	4	Nut - M3 Black Nylon	Order By Description			\$0.35 CAD
SK1	1	QC Sticker	Order by Description			\$0.0094 CAD
Total						\$10.35 CAD

301 11.2 1032A Packaging

302 The parts required to package a 1032A are listed in Table 23.

Table 23: 1032A packing parts

Reference Designation	Qty	Description	Manufacturer	Manufacturer Part Number	Supplier	Cost
N/A	1	Static Shielding Bag 4" X 4" Ziplock	SCS	30044	Digikey	\$0.22 CAD
N/A	1	Static Shielding Bag 1.5" X 2.8" Ziplock	Order by Description			\$0.06 CAD
N/A	1	CORREC-PAK SHIPPER 4 X 4 X 2" ID	Conductive Containers, Inc.	3631	Digikey	\$7.99 CAD
1032-7001	2	1032A ESD Sticker	Jukebox Print			\$4.00 CAD
Total						\$12.27 CAD

303 Section 12

Reduction of Hazardous Materials

304 Compliance declarations, in BOM order.

306 **12.1 MG Chemicals 4900**

Table 24: MG Chemicals 4900 RoHS Compliance

Declaration for MG Chemicals 4900 -
<https://www.mgchemicals.com/downloads/msds/01%20English%20Can-USA%20SDS/sds-4900-4917.pdf>



ISO 9001:2015 Quality Management System
 SAI Global File #004008
 Burlington, Ontario, Canada

SAC305 NO CLEAN SOLDER WIRE

4900-4917

California Proposition 65 (Chemicals known to cause cancer or reproductive toxicity, USA)

This product does not contain any of the listed substances.

Europe

RoHS (Restriction of Hazardous Substances Directive)

This product does not contain any lead, cadmium, mercury, hexavalent chromium, PBB's, PBDE's, DEHP, BBP, DBP, or DIBP and complies with European RoHS regulations.

WEEE (Waste Electrical and Electronic Equipment Directive)

This product is not a piece of electrical or electronics equipment, and is therefore not governed by this regulation.

Section 16: Other Information

SDS Prepared by MG Chemical's Regulatory Department

Date of Review 06 March 2020

Supersedes 09 July 2019

Reason for Changes: Update to the emergency phone number information.

Reference

1) ACGIH 2017 TLVs and BEIs: Based on the documentation of the threshold limit values for chemical substances and physical agents & biological exposure indices, American Conference of Governmental of Industrial Hygienist Cincinnati, OH (2017).

2) All toxicological data were checked against the RTECS (Registry of Toxic Effects of Chemical Substances®)

Section continued on the next page

Page **12 of 13**

Date of Revision: 06 March 2020 / Ver. 3.01

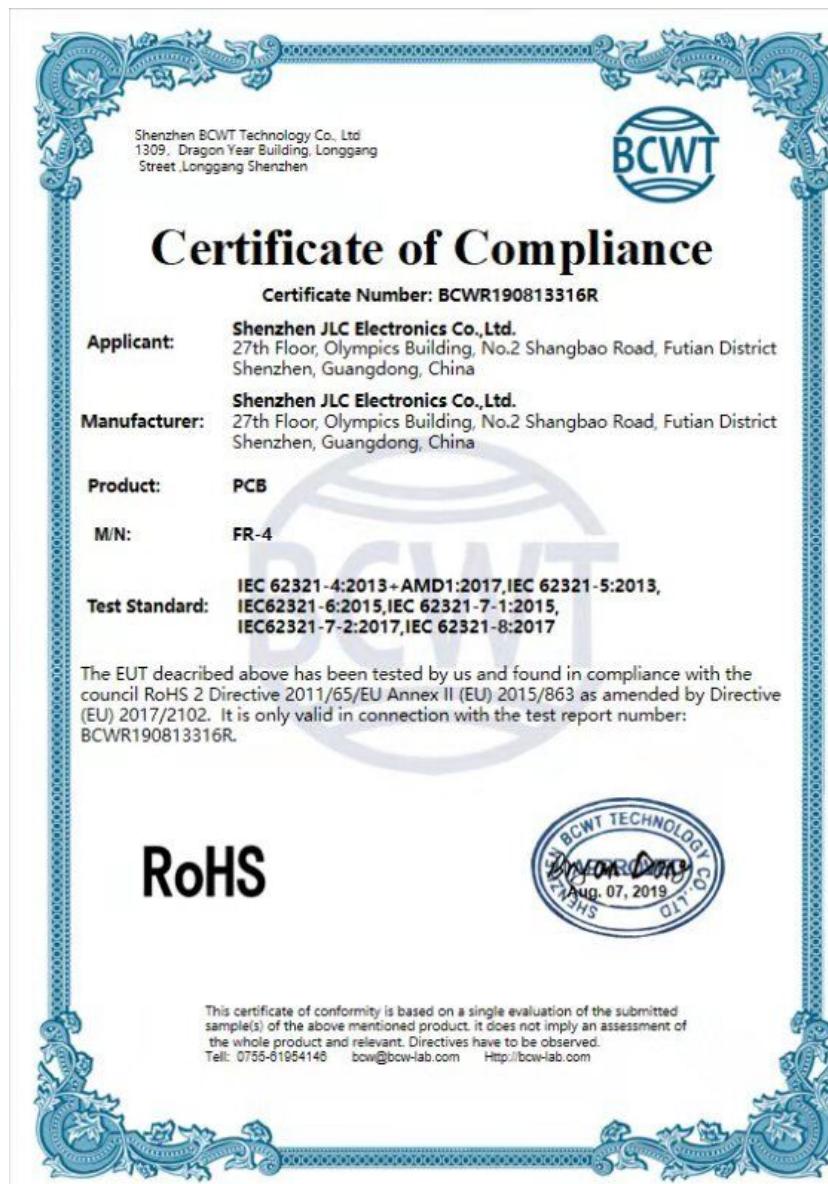
307 12.2 JLC lead-free PCB

Table 25: JLC PCB RoHS Compliance

Declaration for JLCPBCB lead-free PCBs - <https://s3.amazonaws.com/helpscout.net/docs/assets/59f1de7804286313cffbb22c/images/5d4d09562c7d3a036965d6a3/ROHS-Certificate-of-Compliance.jpg>

ROHS-Certificate-of-Compliance.jpg 566x800 pixels

2022-08-16, 23:45



<https://s3.amazonaws.com/helpscout.net/docs/assets/59f1de7804286313cffbb22c/images/5d4d09562c7d3a036965d6a3/ROHS-Certificate-of-Compliance.jpg>

Page 1 of 1

308 **12.3 PARALIGHT A3880E**

Table 26: PARALIGHT A3880E RoHS Compliance

Declaration for PARALIGHT A3880E - Received via e-mail

**Test Report**

No. SHAEC2210695901

Date: 30 Jul 2022

Page 1 of 10

Client Name : PARALIGHT LIANYUNGANG ELECTRONICS CO.,LTD.

Client Address : Economic Development Zone, Guannan County, Lianyungang City, Jiangsu Province

Sample Name : DISPLAY LED

The above sample(s) and information were provided by the client.

SGS Job No. : SP22-015593 - SH

Date of Sample Received : 25 Jul 2022

Testing Period : 25 Jul 2022 - 30 Jul 2022

Test Requested : Selected test(s) as requested by the client.

Test Method(s) : Please refer to next page(s).

Test Result(s) : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Cadmium, Lead, Mercury, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services (Shanghai) Co., Ltd.

Jenny Lan
Approved Signatory



28646128



Unless otherwise agreed in writing, this document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <http://www.sgs.com/en/Terms-and-Conditions.aspx>, for electronic format documents, under the Terms and Conditions of Electronic Delivery, available on request or accessible at <http://www.sgs.com/en/Terms-and-Conditions.aspx>. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained herein reflects the Company's findings at the time of its intervention only and within the limits of its intervention. The Company's intervention does not extend to the customer's installation. Consequently, the Company cannot be held liable for a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced except in full, without prior written approval of the Company. Any unauthorized alteration, forgery or falsification of the content or purpose of this document or any part thereof may result in prosecution to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.

Attention: To check the authenticity of testing /inspection report & certificate, please contact us at telephone: (86-755) 8307 1443,

or e-mail: sales.sgs@sgs.com or www.sgs.com.

3rd Building, No.889 Yizhan Road, Xuhui District, Shanghai China 200233 I E&E (86-21)61402553 I E&E (86-21)64953679 www.sgsgroup.com.cn

中国·上海·徐汇区宜山路889号3号楼 邮编: 200233 I HL (86-21)61402594 I HL (86-21)61156899 e.sgs.china@sgs.com

Member of the SGS Group (SGS SA)

309 **12.4 Molex 0022284020**

Table 27: Molex 0022284020 RoHS Compliance

Declaration for Molex 0022284020 - https://www.molex.com/datasheets/rohspdf/0022284020_rohs.pdf**RoHS Certificate of Compliance**

06/29/2022

Molex is committed to managing the use of chemical substances in accordance with governmental regulations, industry standards, and customer-specific requirements in order to protect the environment. For each part listed, this document provides:

- EU RoHS Compliance Status.** EU RoHS status is declared per Directive 2011/65/EU and its subsequent amendments, including the Directive EU 2015/863 which additionally prohibited four phthalates. Homogeneous materials of parts that are compliant to this legislation have less than 0.1% by weight each of lead, mercury, hexavalent chromium, PBB, PBDE, DBP, BBP, DIBP, DEHP, and 0.01% by weight of cadmium. In situations where an exemption applies, the preceding limits, corresponding to the exempted substance(s), may be higher.

Molex's sole liability for incorrectly certifying a product shall be either replacement of the Molex product or, alternatively and in the sole discretion of Molex, return of the purchase price paid for the relevant Molex product.

For additional information regarding Molex's environmental initiatives and further explanation of this information, please visit www.molex.com

Haim Eliyahu
Director, Global Product Stewardship

Table A

Molex Part Number	Part Description	RoHS Compliance Status
0022284020	KK 254 Breakaway Header, Vertical, 2 Circuits, Tin (Sn) Plating, Mating Pin Length 6.09mm	Compliant

310 **12.5 Cixi ZY28**

Table 28: Cixi ZY28 Compliance

Declaration for Cixi ZY28 -
<http://27696974.s21i.faiusr.com/2/ABUIABACGAAghLXJiwYogKav1QYwoAY46wg.jpg>

Certificate of Compliance

Certificate Number: BSTDG190612860702CC

Applicant	: CIXI ZHONGYI ELECTRONICS FACTORY Yuxiang Road, Xiaolin Town 315321 Cixi City Zhejiang Province China
Manufacturer	: CIXI ZHONGYI ELECTRONICS FACTORY Yuxiang Road, Xiaolin Town 315321 Cixi City Zhejiang Province China
Product Name	: BREAD BOARD
Test Standard	: IEC 62321-4:2013+AMD1:2017, IEC 62321-5:2013, IEC 62321-6:2015, IEC 62321-7-1:2015, IEC 62321-7-2:2017, IEC 62321-8:2017
As shown in the Test Report No.	: BSTDG190612860702CR

The EUT described above has been tested by us and found in compliance with the council RoHS 2 Directive 2011/65/EU Annex II (EU) 2015/863 as last amended by Directive (EU) 2017/2102. This certificate is only valid in conjunction with the test report.

RoHS





Tony Qian
Approved Signatory
Jun.10, 2019

Dongguan BST Testing Co., Ltd
Add: A1201-1204 Xinsanqi of Dongbao Road, Dongcheng District, Dongguan, Guangdong, China
Certificate Search: <http://www bst-lab com>, Tel: 400-8829628, 800-9990305, E-mail: christina@bst-lab.com

311 **12.6 Stackpole RMCF0603FT10K0**

Table 29: Stackpole RMCF0603FT10K0 RoHS Compliance

Declaration for Stackpole RMCF0603FT10K0 -
https://www.seiselect.com/catalog/SEI-RoHS_Compliance_Status.pdf



Resistors						
Standard Product Series	Description	Package / Termination Type	Standard Series RoHS Compliant	Lead-Free Termination Composition	Lead-Free Mfg. Effective Date (Std Product Series)	Lead-Free Effective Date Code (YY/WW)
NSP	Ceramic Housed - Consumer Grade Leaded Resistor <i>DISCONTINUED (May 3, 2013)</i>	Axial	YES	99.3/0.7 Sn/Cu	Jan-04	04/01
NSZ	Ceramic Housed Wirewound Resistor with Specialty Leads	Radial	YES	99.3/0.7 Sn/Cu	Jan-04	04/01
NVM	Ceramic Housed Vertical Mount Wirewound Resistor (Standard WW)	Radial	YES	100% Matte Sn	Always	Always
NWW	General Purpose and Precision Leaded Wirewound Resistor - Conformal Coated - Non-Inductive	Axial	YES	100% Matte Sn	Jan-06	06/01
PCB	Ceramic Housed Leaded Wirewound Resistor - PC Mount <i>DISCONTINUED (July 1, 2014)</i>	Radial	YES	100% Matte Sn	Always	Always
RACF	Thick Film Surface Mount Chip Resistor Array Concave Terminations <i>DISCONTINUED (Nov. 15, 2019)</i>	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Jan-04	04/01
RAF	Thick Film Surface Mount Chip Resistor Array Flat Terminations	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Jul-04	04/27
RAVF	Thick Film Surface Mount Chip Resistor Array Convex Terminations	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Jan-04 (Japan) Jul-04 (Taiwan)	04/01 04/27
RAVS	Convex Anti-Sulfur Chip Resistor Array	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Always	Always
RC	Carbon Composition Leaded Resistor	Axial	YES	100% Matte Sn	Jan-86	86/01
RGC	Semi-Precision Thick Film Surface Mount Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Jul-04	04/27
RHC	High Power Thick Film Surface Mount Chip Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Jul-04	04/27
RMCA	Automotive Grade Thick Film Chip Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Always	Always
RMCF	General Purpose Thick Film Surface Mount Chip Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Jan-04 (Japan) Jan-05 (Taiwan, China)	04/01 05/01
RMCG	Gold Barrier Thick Film Surface Mount Chip Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Jan-06	06/01
RMCP	General Purpose High Power Thick Film Chip Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Always	Always
RMCS	Sulfur Resistant Thick Film Surface Mount Chip Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Always	Always
RMCW	Wide Termination Thick Film Chip Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Always	Always
RMEF	General Purpose Thick Film Surface Mount Chip Resistor 100% Lead Free	SMD	YES	100% Mtte Sn over Ni	Always	Always
RNCF	Precision Thin Film Surface Mount Chip Resistor	SMD	YES	100% Matte Sn over Ni	May-04	04/18
RNCH	Anti-Corrosive Tantalum Nitride Replacement Surface Mount Chip Resistor	SMD	YES	100% Matte Sn over Ni	Always	Always
RNCP	High Power Anti-Sulfur Thin Film Chip Resistor	SMD	YES	100% Matte Sn over Ni	Always	Always
RNCS	Anti-Corrosive Tantalum Nitride Replacement Surface Mount Chip Resistor	SMD	YES	100% Matte Sn over Ni	May-04	04/18
RNCW	Thin Film Wire-Bondable Chip Resistor - <i>DISCONTINUED (Jan. 17, 2018)</i>	SMD	YES	Gold Plating	Always	Always
RNF	General Purpose Metal Film Leaded Resistor	Axial	YES	99.3/0.7 Sn/Cu 100% Matte Sn	Apr-05 (Japan) Jan-04 (Taiwan, China)	05/14 04/01
RNMF	General Purpose Mini Metal Film Leaded Resistor	Axial	YES	99.3/0.7 Sn/Cu 100% Matte Sn	Apr-05 (Japan) Jan-04 (Taiwan, China)	05/14 04/01
RNS	Ultra-Miniature Metal Film Resistor	Axial	YES	100% Matte Sn	Always	Always

Note (1): RoHS Compliant by means of exemption 7c-l.

Rev Date: 3/1/2022

3

www.seiselect.com
marketing@seiselect.com

This specification may be changed at any time without prior notice.
 Please confirm technical specifications before you order and/or use.

312 **12.7 Stackpole RMCF0603FT649R**

Table 30: Stackpole RMCF0603FT649R RoHS Compliance

Declaration for Stackpole RMCF0603FT649R -
https://www.seiselect.com/catalog/SEI-RoHS_Compliance_Status.pdf



Resistors						
Standard Product Series	Description	Package / Termination Type	Standard Series RoHS Compliant	Lead-Free Termination Composition	Lead-Free Mfg. Effective Date (Std Product Series)	Lead-Free Effective Date Code (YY/WW)
NSP	Ceramic Housed - Consumer Grade Leaded Resistor <i>DISCONTINUED (May 3, 2013)</i>	Axial	YES	99.3/0.7 Sn/Cu	Jan-04	04/01
NSZ	Ceramic Housed Wirewound Resistor with Specialty Leads	Radial	YES	99.3/0.7 Sn/Cu	Jan-04	04/01
NVM	Ceramic Housed Vertical Mount Wirewound Resistor (Standard WW)	Radial	YES	100% Matte Sn	Always	Always
NWW	General Purpose and Precision Leaded Wirewound Resistor - Conformal Coated - Non-Inductive	Axial	YES	100% Matte Sn	Jan-06	06/01
PCB	Ceramic Housed Leaded Wirewound Resistor - PC Mount <i>DISCONTINUED (July 1, 2014)</i>	Radial	YES	100% Matte Sn	Always	Always
RACF	Thick Film Surface Mount Chip Resistor Array Concave Terminations <i>DISCONTINUED (Nov. 15, 2019)</i>	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Jan-04	04/01
RAF	Thick Film Surface Mount Chip Resistor Array Flat Terminations	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Jul-04	04/27
RAVF	Thick Film Surface Mount Chip Resistor Array Convex Terminations	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Jan-04 (Japan) Jul-04 (Taiwan)	04/01 04/27
RAVS	Convex Anti-Sulfur Chip Resistor Array	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Always	Always
RC	Carbon Composition Leaded Resistor	Axial	YES	100% Matte Sn	Jan-86	86/01
RGC	Semi-Precision Thick Film Surface Mount Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Jul-04	04/27
RHC	High Power Thick Film Surface Mount Chip Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Jul-04	04/27
RMCA	Automotive Grade Thick Film Chip Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Always	Always
RMCF	General Purpose Thick Film Surface Mount Chip Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Jan-04 (Japan) Jan-05 (Taiwan, China)	04/01 05/01
RMCG	Gold Barrier Thick Film Surface Mount Chip Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Jan-06	06/01
RMCP	General Purpose High Power Thick Film Chip Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Always	Always
RMCS	Sulfur Resistant Thick Film Surface Mount Chip Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Always	Always
RMCW	Wide Termination Thick Film Chip Resistor	SMD	YES ⁽¹⁾	100% Matte Sn over Ni	Always	Always
RMEF	General Purpose Thick Film Surface Mount Chip Resistor 100% Lead Free	SMD	YES	100% Mtte Sn over Ni	Always	Always
RNCF	Precision Thin Film Surface Mount Chip Resistor	SMD	YES	100% Matte Sn over Ni	May-04	04/18
RNCH	Anti-Corrosive Tantalum Nitride Replacement Surface Mount Chip Resistor	SMD	YES	100% Matte Sn over Ni	Always	Always
RNCP	High Power Anti-Sulfur Thin Film Chip Resistor	SMD	YES	100% Matte Sn over Ni	Always	Always
RNCS	Anti-Corrosive Tantalum Nitride Replacement Surface Mount Chip Resistor	SMD	YES	100% Matte Sn over Ni	May-04	04/18
RNCW	Thin Film Wire-Bondable Chip Resistor - <i>DISCONTINUED (Jan. 17, 2018)</i>	SMD	YES	Gold Plating	Always	Always
RNF	General Purpose Metal Film Leaded Resistor	Axial	YES	99.3/0.7 Sn/Cu 100% Matte Sn	Apr-05 (Japan) Jan-04 (Taiwan, China)	05/14 04/01
RNMF	General Purpose Mini Metal Film Leaded Resistor	Axial	YES	99.3/0.7 Sn/Cu 100% Matte Sn	Apr-05 (Japan) Jan-04 (Taiwan, China)	05/14 04/01
RNS	Ultra-Miniature Metal Film Resistor	Axial	YES	100% Matte Sn	Always	Always

Note (1): RoHS Compliant by means of exemption 7c-l.

Rev Date: 3/1/2022

3

www.seiselect.com
marketing@seiselect.com

This specification may be changed at any time without prior notice.
 Please confirm technical specifications before you order and/or use.

313 12.8 Nexperia MMBT2222A

Table 31: Nexperia MMBT2222A RoHS Compliance

Declaration for Nexperia MMBT2222A - <https://www.nexperia.com/dam/jcr:96c06925-615d-4095-b779-3718c9f9cdde/Nexperia%20-%20Statement%20on%20RoHS.pdf>



July 2022

CERTIFICATE OF COMPLIANCE - RoHS Declaration -

Nexperia B.V. declares that its semiconductor products (including homogeneous sub-components, pins, casing, and internal parts) are designed to be:

RoHS compliant by meeting the requirements defined under Directive 2011/65/EU of 2011-07-21, amended by Directive (EU) 2015/863 of 2015-03-31, on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE):

RoHS Restricted Substance	Allowable Limit
Cadmium (Cd)	100 ppm (0.01 weight %)
Mercury (Hg)	1000 ppm (0.1 weight %)
Hexavalent chromium (Cr ⁶⁺)	1000 ppm (0.1 weight %)
Lead (Pb)	1000 ppm (0.1 weight %)
Polybrominated biphenyls (PBBs)	1000 ppm (0.1 weight %)
Polybrominated diphenyl ethers (PBDEs)*	1000 ppm (0.1 weight %)
Bis(2-ethylhexyl) phthalate (DEHP)	1000 ppm (0.1 weight %)
Butyl benzyl phthalate (BBP)	1000 ppm (0.1 weight %)
Dibutyl phthalate (DBP)	1000 ppm (0.1 weight %)
Diisobutyl phthalate (DIBP)	1000 ppm (0.1 weight %)

* Including decabromodiphenylether (decaBDE).

All Nexperia devices are RoHS compliant. Nexperia devices contain no more than 0.1 % lead (Pb) by weight per homogeneous material or may contain lead (Pb) in applications allowed by the RoHS Directive. Nexperia may apply any of the following RoHS exemptions to RoHS compliant Nexperia devices:

RoHS Exemption	RoHS Exemption Description
7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
7(c)-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound

Nexperia devices can be recognized by the "RoHS compliant" logo on the box label. In addition, products that do not make use of any exemption on the use of lead can be recognized by the "Lead-free" logo.

To facilitate customer requirements and to verify Nexperia product compliance, Nexperia material content information is available here:
<https://www.nexperia.com/quality/download-multiple-product-compositions.html>

Page 1 of 2

Nexperia B.V. • Jonkerbosplein 52 • 6534 AB Nijmegen • 6050 AA Nijmegen • The Netherlands
 K.V.K. 66264111 0000 • VAT.NO. NL856469397801 • Citibank London 18190372 (EUR) • IBAN GB14CITI18500818190372 • BIC CITIGB2L
 Citibank London 18190402 (USD) • IBAN GB77CITI18500818190402 • BIC CITIGB2L

nexperia.com

314 **12.9 M3 8mm Nylon Screw**

Table 32: M3 8mm Nylon Screw RoHS Compliance

Declaration for M3 8mm Nylon Screw - N/A
 <p>A photograph showing a clear plastic bag filled with numerous small, black, cylindrical M3 8mm Nylon Screws. A white rectangular label is pinned to the top center of the bag. The label contains the following text in Chinese:</p> <p>合格证 品名:尼龙螺丝 型号:十字M3*8 数量: 1000 材料: PA66 ROHS</p>

315 **12.10 M3 11mm Nylon Standoff**

Table 33: M3 11mm Nylon Standoff RoHS Compliance

Declaration for M3 11mm Nylon Standoff - N/A
 <p>合格证 PRODUCT QUALIFIED CARD</p> <p>产品名称: 六角隔柱</p> <p>规格型号: M3-11</p> <p>数 量: 1000 只</p> <p>检 验 员: _____</p> <p>材 质: PA66 ROHS</p>

316 **12.11 M3 Nylon Bolt**

Table 34: M3 Nylon Bolt RoHS Compliance

Declaration for M3 Nylon Bolt - N/A